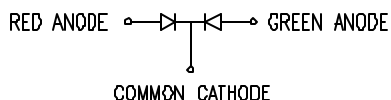
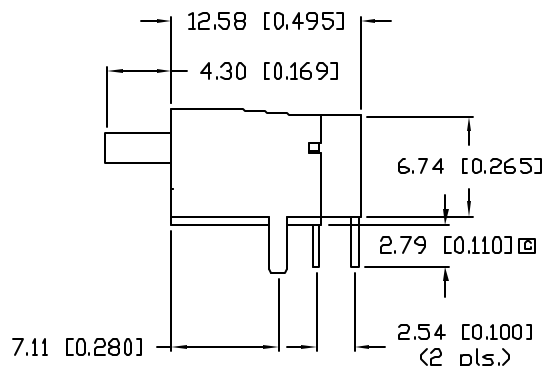
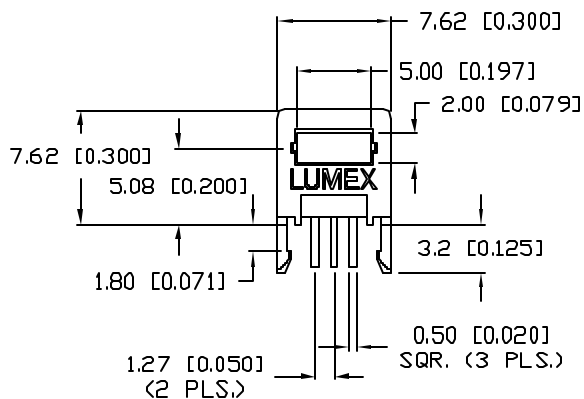
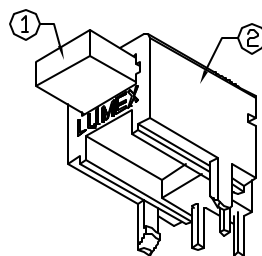
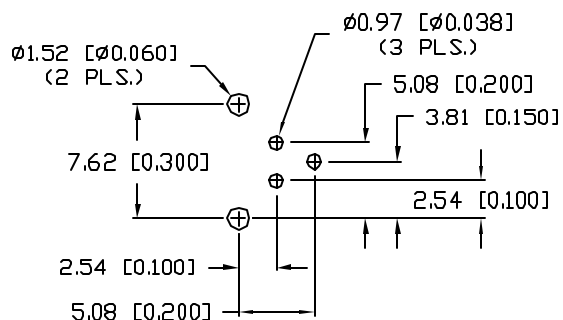


UNCONTROLLED DOCUMENT

UNDER REVISION



HOLE PATTERN LAYOUT



SC:0.50	PART NUMBER	REV.
	SSF-LXH2579IGW	D
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10163.	5.8.96
B	E.C.N. #10226.	8.16.96
C	E.C.N. #10BRDR. & #10416.	2.24.98
D	E.C.N. #10BRDR. & REDRAWN.	2.24.98

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		635 (RED)		nm	
		565 (GREEN)		nm	
FORWARD VOLTAGE (R/G)		2.0/2.2	2.5/2.6	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_r=100\mu\text{A}$
AXIAL INTENSITY (R/G)		14/8		mcad	$I_f=20\text{mA}$
VIEWING ANGLE		110		$2x$ theta	
EMITTED COLOR:	RED/GREEN				
EPOXY LENS FINISH:	MILKY WHITE DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	COLORS	MAX	UNITS
PEAK FORWARD CURRENT*		150	mA
STEADY CURRENT	(R/G)	30/25	mA
POWER DISSIPATION		105	mW
DERATE FROM 25°C		-1.2	mW/°C
OPERATING, STORAGE TEMP.		-40 TO +85	°C
SOLDERING TEMP.		+260	°C
2.0mm FROM BODY			3 SEC. MAX

* $t < 10\mu\text{s}$

NOTES:

- SSL-LXH2579IGW, RED/GREEN BICOLOR LED.
- SSH-LXH2579 HOLDER, 94V-0 BLACK NYLON.

UNCONTROLLED DOCUMENT

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN=+0.00 DECIMAL PRECISION MAX.=+0.00 DECIMAL PRECISION

REV.	PART NUMBER
D	SSF-LXH2579IGW

CONFIDENTIAL INFORMATION
 THE INFORMATION CONTAINED IN THIS DOCUMENT IS THE PROPERTY OF LUMEX INC. EXCEPT AS SPECIFICALLY AUTHORIZED IN WRITING BY LUMEX INC, THE HOLDER OF THIS DOCUMENT SHALL KEEP ALL INFORMATION CONTAINED HEREIN CONFIDENTIAL AND SHALL PROTECT SAME IN WHOLE OR IN PART FROM DISCLOSURE AND DISSEMINATION TO ALL THIRD PARTIES.



290 E. HELEN ROAD
 PALATINE, IL 60067-6976
 PHONE: +1.847.359.2790
 US WEB: www.lumex.com
 TW WEB: www.lumex.com.tw

2mm x 5mm TRI LEADED RECTANGULAR INDICATOR,
 BICOLOR RED/GREEN LED, MILKY WHITE DIFFUSED LENS.

RELIABILITY NOTE
 OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:	CHECKED BY:	APPROVED BY:	DATE: 10.3.95
GT			PAGE: 1 OF 1
			SCALE: N/A